ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention

METHOD AND SYSTEM FOR DYNAMIC MODELING AND RECIPE OPTIMIZATION OF SEMICONDUCTOR ETCH PROCESSES

Submision Type: Information Disclosure

Statement

Application Number:

10/523777

EFS ID: 94585

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ISVR1	Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application
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File Listing:

Doc. Name	File Name	Size (Bytes)	Date
			Produced
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us-ids	VOY007US-usidst.xml	956	2005-10-13
us-ids	us-ids.dtd	7763	2005-10-13
us-ids	us-ids.xsl	12026	2005-10-13
package-data	VOY007US-pkda.xml	1761	2005-10-13
package-data	package-data.dtd	27025	2005-10-13
package-data	us-package-data.xsl	19263	2005-10-13
Total files size		68794	

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